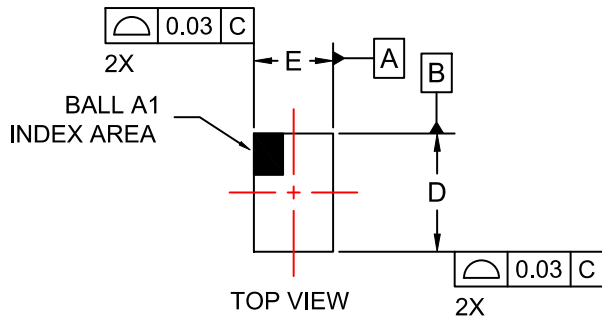


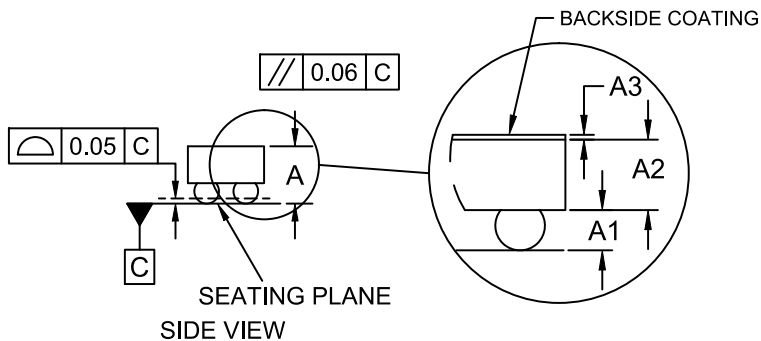
WLCSP6 1.36x0.76x0.581
CASE 567XQ
ISSUE O

DATE 03 APR 2019

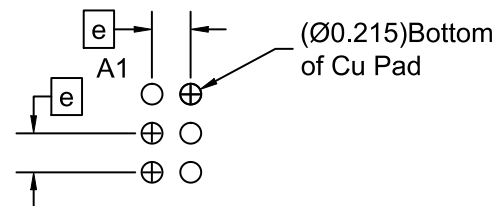
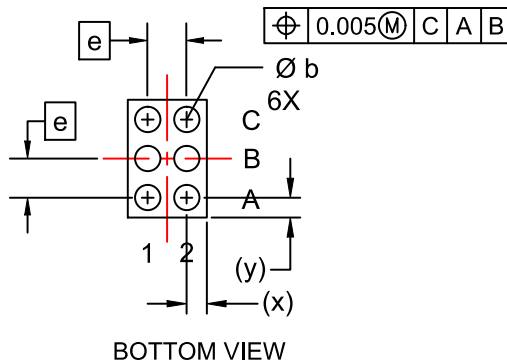


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.540	0.581	0.622
A1	0.183	0.203	0.223
A2	0.335	0.353	0.371
A3	0.022	0.025	0.028
b	0.240	0.260	0.280
D	1.33	1.36	1.39
E	0.73	0.76	0.79
e	0.40 BSC		
x	0.150	0.165	0.180
y	0.250	0.265	0.280



RECOMMENDED MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERING.D.

DOCUMENT NUMBER:	98AON02370H	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	WLCSP6 1.36x0.76x0.581	PAGE 1 OF 1

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.